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April 2, 2004

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
TD	2002/0108743	8-2002	Wirtz			
TD	4,880,052	11-1989	Meyer, IV et al.			
TD	4,577,398	3-1986	Sliwa et al.			
TD	5,688,716	11-1997	DiStefano et al.			
TD	5,583,317	12-1996	Mennucci et al.			
TD	5,777,259	7-1998	Mennucci et al.			
TD	5,987,893	11-1999	Schulz-Harder et al.			
TD	6,014,312	1-2000	Schulz-Harder et al.			
TD	6,317,326	11-2001	Vogel et al.			
TD	4,717,433	1-1988	Weisert et al.			
TD	5,325,913	7-1994	Altoz			
TD	5,526,867	6-1996	Keck et al.			

FOREIGN PATENT DOCUMENTS

DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO

OTHER DOCUMENTS (including Author, Title, Date, Pertinent pages, etc.)

TD	Zheng et al, "Cylindrical Pin-Fin Fan-Sink Heat Transfer and Pressure Drop Correlations", IEEE Trans. Components and Packaging Technology, vol. 25, also ASME/JSME Thermal Engineering Joint Conference Proceedings, paper AJTE99-6197, 1999,
TD	Wirtz, "High Performance Woven Mesh Heat Exchange", F49620-99-1-0286, 1999
TD	"High Performance Woven Mesh Heat Exchange", Research Summary, AFOSR Contractors' Meeting in Turbulence and Rotation Flows, Albuquerque, NM, August 18-19, 1999
TD	Xu et al, "In-Plane Effective Thermal Conductivity of Plain Weave Screen Laminates with Arbitrary Weave Parameters", Paper TED-AJ03-417, 6 th ASME/JSME Thermal Engineering Joint Conference, Hawaii, March 16-20, 2003
TD	Xu et al, "In-Plane Effective Thermal Conductivity of Plain-Weave Screen Laminates", IEEE Trans. on Components and Packaging Tech., vol. 25, #4, 2003. See also Proc. THERMES 2002, pp. 231-242, Millpress, Rotterdam, January 2002
TD	Wirtz et al, "Thermal/Fluid Characteristics of 3-D Woven Mesh Structures as Heat Exchanger Surfaces", IEEE Trans Components and Packaging Technology, vol. 26, 2003, pp.40-47. See also paper 1372, Eighth Intersociety Conference on Thermal Phenomena in Electronic Systems, San Diego, CA
TD	Li et al, "Development of a High-Performance Heat Sink Based on Screen-Fin Technology", Proc 19-th Semiconductor Thermal Measurement and Management Symposium, IEEE 02CH37437, March 6-10, 2003, pp. 53-60

*Examiner

Date Considered

8/1/05

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application.

Form PTO-FB-A820 (Also PTO-1449)